

Product / Package Information

Package	SOT23 - Flip Chip
Body Size	
Lead Count	8
Terminal Finish	100Sn
MS Number	MS012784B + MS012386B

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes
Last Updated	13-Mar-2019

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.38 E-03	87.30	873000	44.99	449860
Thermosets	Phenol Resin	Proprietary	3.80 E-04	4.50	45000	2.32	23189
Thermosets	Epoxy Resin 1	Proprietary	2.54 E-04	3.00	30000	1.55	15459
Thermosets	Epoxy Resin 2	Proprietary	2.54 E-04	3.00	30000	1.55	15459
Others	Others	Proprietary	1.69 E-04	2.00	20000	1.03	10306
Other inorganic materials	Carbon Black	1333-86-4	1.69 E-05	0.20	2000	0.10	1031
Subtotal			8.45 E-03	100.0	1000000	51.53	515304

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.54 E-03	97.5	975000	33.78	337820
Copper & its alloys	Iron	7439-89-6	1.34 E-04	2.35	23500	0.81	8142
Copper & its alloys	Zinc	7440-66-6	6.82 E-06	0.12	1200	0.04	416
Copper & its alloys	Phosphorus	7723-14-0	1.70 E-06	0.03	300	0.01	104
Subtotal			5.68 E-03	100	1000000	34.65	346482

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.29 E-04	100	1000000	3.22	32233

Flux

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Polyglycol ether	9038-95-3	4.73 E-04	82.50	825000	2.88	28822
Other organic materials	Carboxylic acids	68937-68-8	6.59 E-05	11.50	115000	0.40	4018
Other organic materials	Amides from C2-9 Carboxylic acids and Polyethylenimine	68876-81-3	3.44 E-05	6.00	60000	0.21	2096
Subtotal			5.73 E-04	100.00	1000000	3.49	34936

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.12 E-03	100	1000000	6.83	68306

Wafer Bumps

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Cu pillar bump	Tin	7440-31-5	2.33 E-05	98.20	982000	0.14	1423
Cu pillar bump	Silver	7440-22-4	4.28 E-07	1.80	18000	0.00	26
Subtotal			2.38 E-05	100.00	1000000	0.14	1449

UBM

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.63 E-07	79.87	798700	0.003	28
Other inorganic materials	Titanium	7440-32-6	1.17 E-07	20.13	201300	0.0007	7
Subtotal			5.80E-07	100.00	1000000	0.00	35

Polyimide

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Polyimide 1	70485-58-4	2.06 E-05	100.00	1000000	0.13	1254

Package Totals			Weight (g) 1.64 E-02			Percentage (%) 100	PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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